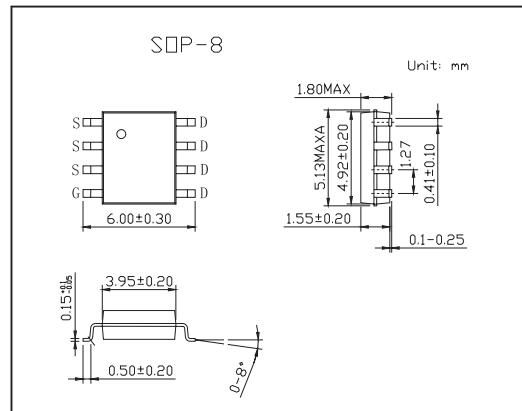
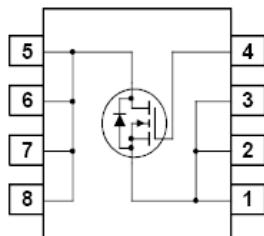


N-Channel UltraFET Trench MOSFET

KDS2572

■ Features

- $R_{DS(ON)} = 0.040 \Omega$ (Typ.), $V_{GS} = 10V$
- $Q_{G(TOT)} = 29nC$ (Typ.), $V_{GS} = 10V$
- Low QRR Body Diode
- Maximized efficiency at high frequencies
- UIS Rated



■ Absolute Maximum Ratings $T_a = 25^\circ C$

| Parameter | Symbol | Rating | Unit |
|--|-----------------|------------|---------------|
| Drain to Source Voltage | V_{DSS} | 150 | V |
| Gate to Source Voltage | V_{GS} | ± 20 | V |
| Drain Current Continuous ($T_c = 25^\circ C$) *1 | I_D | 4.9 | A |
| Drain Current Continuous ($T_c = 100^\circ C$) *1 | | 3.1 | A |
| Power dissipation | P_D | 2.5 | W |
| Derate above $25^\circ C$ | | 20 | $mW/^\circ C$ |
| Operating and Storage Temperature | T_J, T_{STG} | -55 to 150 | °C |
| Thermal Resistance Junction to Case | $R_{\theta JC}$ | 25 | °C/W |
| Thermal Resistance Junction to Case at 10 seconds *2 | $R_{\theta JA}$ | 50 | °C/W |
| Thermal Resistance Junction to Case at steady state *2 | $R_{\theta JA}$ | 85 | °C/W |

*1 $V_{GS} = 10V$, $R_{QJA} = 50^\circ C/W$

*2 $R_{\theta JA}$ is measured with 1.0in² copper on FR-4 board

KDS2572

■ Electrical Characteristics Ta = 25°C

| Parameter | Symbol | Testconditons | Min | Typ | Max | Unit |
|-----------------------------------|---------------------|--|-----|-------|-------|------|
| Drain to Source Breakdown Voltage | BVDSS | Id = 250mA, VGS = 0V | 150 | | | V |
| Zero Gate Voltage Drain Current | IDSS | VDS = 120V, VGS = 0V | | 1 | | μ A |
| | | VDS = 120V, VGS = 0V, Tc = 150°C | | | 250 | |
| Gate to Source Leakage Current | IGSS | VGS = ±20V | | | ±100 | nA |
| Gate to Source Threshold Voltage | VGS(TH) | VGS = VDS, Id = 250mA | 2 | | 4 | V |
| Drain to Source On Resistance | rDS(ON) | Id = 4.9A, VGS = 10V | | 0.040 | 0.047 | Ω |
| Drain to Source On Resistance | rDS(ON) | Id = 4.9A, VGS = 6V | | 0.044 | 0.053 | Ω |
| Input Capacitance | Ciss | VDS = 25V, VGS = 0V, f = 1MHz | | 2050 | | pF |
| Output Capacitance | Coss | | | 220 | | pF |
| Reverse Transfer Capacitance | Crss | | | 48 | | pF |
| Total Gate Charge at 10V | Qg(TOT) | VGS=0V to 10V, VDD=75V, Id=4.9A, Ig=1.0mA | | 29 | 38 | nC |
| Threshold Gate Charge | Qg(TH) | VGS=0V to 2V, VDD=75V, Id=4.9A, Ig=1.0mA | | 4 | 6 | nC |
| Gate to Source Gate Charge | Qgs | VDD = 75V, Id = 4.9A, Ig = 1.0mA | | 8 | | nC |
| Gate to Drain "Miller" Charge | Qgd | | | 6 | | nC |
| Gate Charge Threshold to Plateau | Qgs2 | | | 4 | | nC |
| Turn-On Time | t _{ON} | VDD = 75V, Id = 4.9A, VGS = 10V, RG = 10 Ω | | | 27 | ns |
| Turn-On Delay Time | t _{d(ON)} | | | | 14 | ns |
| Rise Time | t _r | | | | 4 | ns |
| Turn-Off Delay Time | t _{d(OFF)} | | | | 44 | ns |
| Fall Time | t _f | | | | 22 | ns |
| Turn-Off Time | t _{OFF} | | | | 100 | ns |
| Source to Drain Diode Voltage | VSD | ISD = 4.9A | | | 1.25 | V |
| | | ISD = 3.1A | | | 1.0 | V |
| Reverse Recovery Time | t _{rr} | ISD = 4.9A, dISD/dt = 100A/ μ s | | | 72 | ns |
| Reverse Recovered Charge | QRR | ISD = 4.9, dISD/dt = 100A/ μ s | | | 158 | nC |